

Title (en)

METHOD FOR PROMOTING ADHESION BETWEEN DIELECTRIC SUBSTRATES AND METAL LAYERS

Title (de)

VERFAHREN ZUR FÖRDERUNG DER HAFTUNG ZWISCHEN DIELEKTRISCHEN SUBSTRATEN UND METALLSCHICHTEN

Title (fr)

PROCÉDÉ PERMETTANT DE FAVORISER L'ADHÉRENCE ENTRE DES SUBSTRATS DIÉLECTRIQUES ET DES COUCHES MÉTALLIQUES

Publication

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Application

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Abstract (en)

[origin: EP2644744A1] The present invention relates to novel processes for metallization of dielectric substrate surfaces applying organosilane compositions followed by oxidative treatment. The method results in metal plated surfaces exhibiting high adhesion between the substrate and the plated metal while at the same time leaves the smooth substrate surface intact.

IPC 8 full level

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